





New HTV

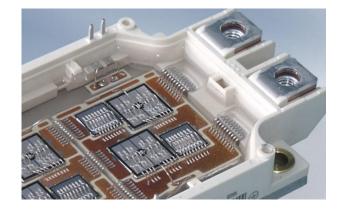
high temperature vacuum reflow soldering

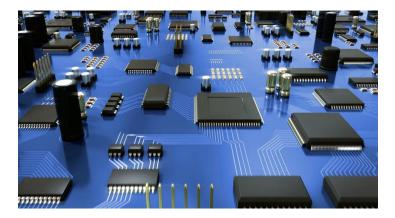


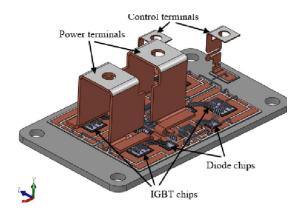


Buzzwords Area of Industry & Applications

- Power Electronics
- Semiconductor Industry
- IGBT's
- DBC
- Substrate
- Preforms
- Die Attach
- Heat spreader attach
- Flux-free soldering
- No oxidation on copper or similar surfaces
- Heatsink
- PINK (Vadu)
- Budatec
- Centrotherm









Process

The HTV system can cover different processes In general, it is a reflow process with/and/or

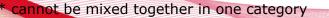
- Atmosphere
- Formic Acid* (CH₂O₂)
- Hydrogen* (H₂) (100 %)
- Nitrogen (N₂) (always needed)

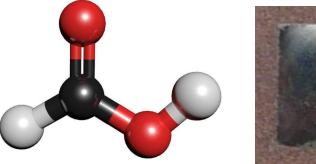
Temperature

- High temperature solder*
- SAC 305*

Process

- Vacuum
- Preforms with Flux*
- Preforms without Flux*







→ The system can be chosen in a combination of Atmosphere & Temperature & Process



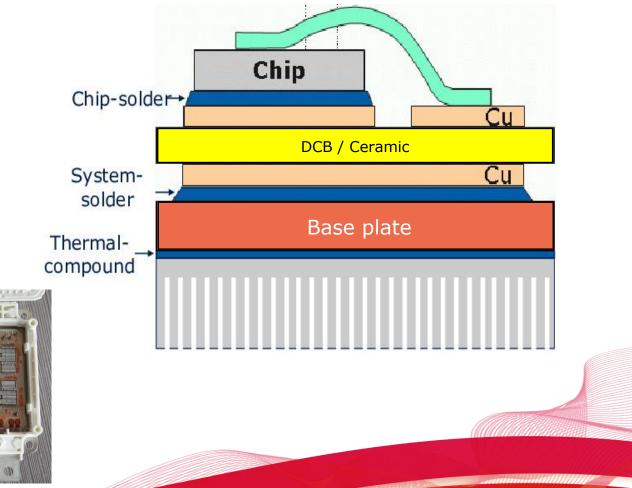
Possible Applications

The HTV system can be used for different applications

Applications

- IGBT
- DCB
- Die Attach
- Opto Laser
- Heatsink
- In general cooper surfaces
- Vapour Phase substitution
- Cleaning process



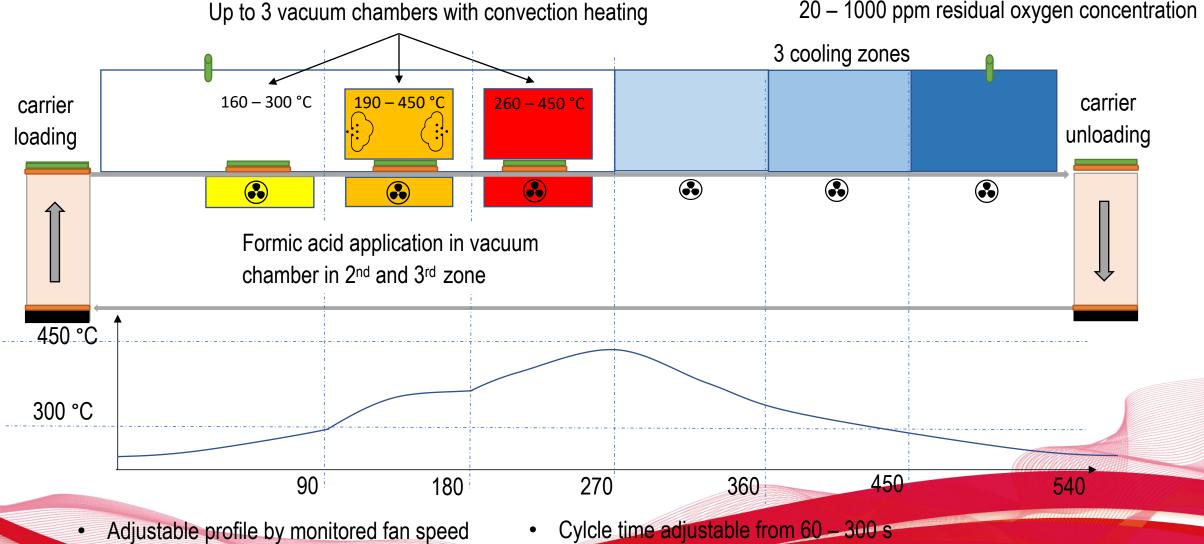




HTV system schematic – example

Vacuum with formic acid

oxygen sensors for nitrogen control for 20 – 1000 ppm residual oxygen concentration



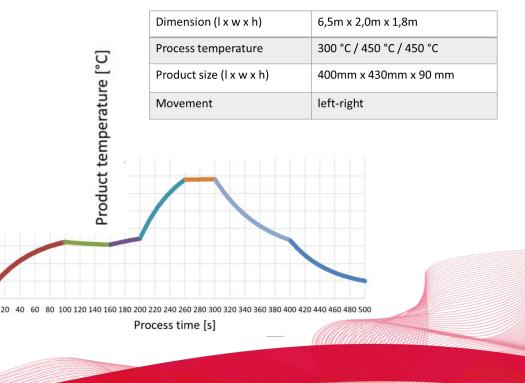


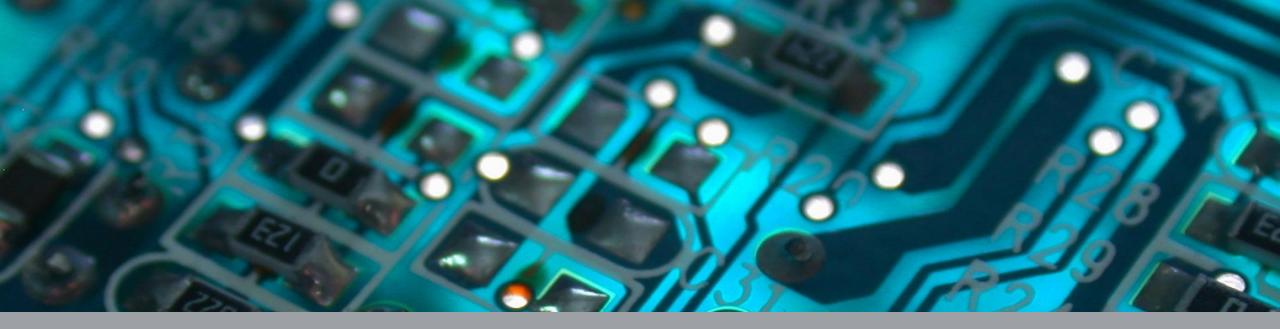
Hight Temp Vacuum Inline Reflow

High Temperature Vacuum Inline Soldering HARDWARE A D V A N T A G E S

- Full convection heating concept
- Flexible for different products in same process
- One general work piece carrier flexilbe inlay (can be also provided by customer)
- No toolings needed (for soldering)
- Intelligent safety concept
 - Closed system
 - N₂ atmosphere (100 ppm residual oxygen)
 - Intelligent gas warning detectors
- More efficient vaporizer process no bubbler process
 - \rightarrow less N₂ and formic acid needed
- 3 heating zones, 3 cooling zones
- 3 optional vacuum chambers in heating zones
- Cycle time from 60 180 s
- Heat transfer controllable via fan speed
- System for different processes and needs







THANK YOU!

